IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Taylor R. Efland

Docket No.:

TI-30963.1

Serial No.:

Examiner:

TBD

Filed: Herewith

Art Unit.:

TBD

Thermally Enhanced Semiconductor Chip

Conf. No.:

TBD

Having Integrated Bonds Over Active Circuits

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner For Patents Attn: Official Drafts Person

Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.

Submitted herewith are 2 sheets of formal drawings.

No fee is believed by Applicant to be due; however, the Commissioner is hereby authorized and requested to charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

Texas Instruments Incorporated P. O. Box 655474, MS 3999 Dallas, Texas 75265

(972) 917-5653

Michael K. Skrehot

Attorney for Applicants

Reg. No.: 36,682